



## 14 Gbps, FAST RISE TIME XOR / XNOR GATE

#### Typical Applications

The HMC725LC3C is ideal for:

- 16 G Fiber Channel
- RF ATE Applications
- Broadband Test & Measurement
- Serial Data Transmission up to 14 Gbps
- Digital Logic Systems up to 14 GHz

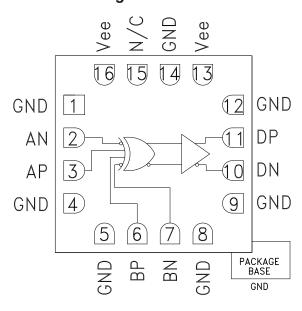
#### **Features**

Inputs Terminated Internally to 50 Ohms
Differential or Single-Ended Operation
Fast Rise and Fall Times: 19 / 18 ps
Low Power Consumption: 230 mW typ.

Propagation Delay: 105 ps Single Supply: -3.3 V

16 Lead Ceramic 3x3 mm SMT Package: 9 mm<sup>2</sup>

#### **Functional Diagram**



#### **General Description**

The HMC725LC3C is a XOR/XNOR gate function designed to support data transmission rates of up to 14 Gbps, and clock frequencies as high as 14 GHz.

All differential inputs to the HMC725LC3C are CML and terminated on-chip with 50 Ohms to the positive supply, GND, and may be DC or AC coupled. The differential CMI outputs are source terminated to to 50 Ohms and may also be AC or DC coupled. Outputs can be connected directly to a 50 Ohm ground-terminated system or drive devices with CML logic input. The HMC725LC3C operates from a single -3.3 V supply and is available in ROHS-compliant 3x3 mm SMT package.

#### Electrical Specifications, $T_A = +25$ °C, Vee = -3.3 V

Parameter	Conditions	Min.	Тур.	Max	Units
Power Supply Voltage		-3.6	-3.3	-3.0	V
Power Supply Current			70		mA
Maximum Data Rate			14		Gbps
Maximum Clock Rate			14		GHz
Input Voltage Range		-1.5		0.5	V
Input Differential Range		0.1		2.0	Vp-p
Input Return Loss	Frequency <14 GHz		10		dB
Output Amplitude	Single-Ended, peak-to-peak		550		mVp-p
Output Amplitude	Differential, peak-to-peak		1100		mVp-p
Output High Voltage			-10		mV
Output Low Voltage			-560		mV
Output Rise / Fall Time	Differential, 20% - 80%		19 / 18		ps





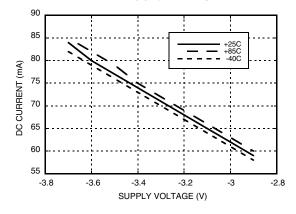
# 14 Gbps, FAST RISE TIME XOR / XNOR GATE

#### **Electrical Specifications** (continued)

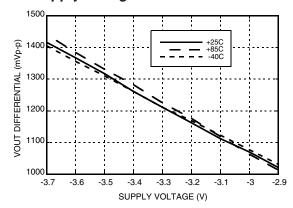
Parameter	Conditions	Min.	Тур.	Max	Units
Output Return Loss	Frequency <14 GHz		10		dB
Small Signal Gain			27		dB
Random Jitter Jr	rms			0.2	ps rms
Deterministic Jitter, Jd	peak-to-peak, 2 <sup>15</sup> -1 PRBS input [1]		2		ps, p-p
Propagation Delay, td			105		ps

<sup>[1]</sup> Deterministic jitter calculated by simultaneously measuring the jitter of a 300 mV, 13 GHz, 215-1 PRBS input, and a single-ended output

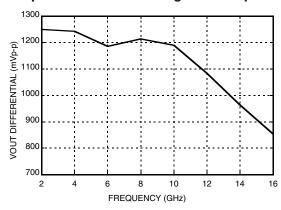
#### DC Current vs. Supply Voltage [1]



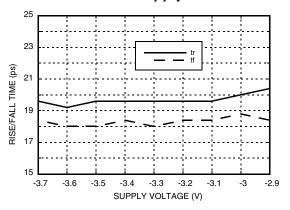
# Output Differential Voltage vs. Supply Voltage [2]



## Output Differential Voltage vs. Frequency [3]



#### Rise / Fall Time vs. Supply [1]



[[1] Data rate = 13 Gbps

[2] Frequency = 10 GHz

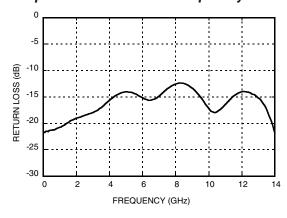
[3] Vee = -3.3 V



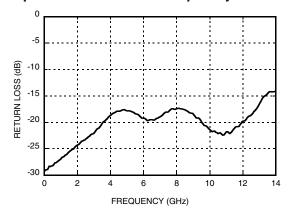


# 14 Gbps, FAST RISE TIME XOR / XNOR GATE

#### **Output Return Loss vs. Frequency**



#### Input Return Loss vs. Frequency

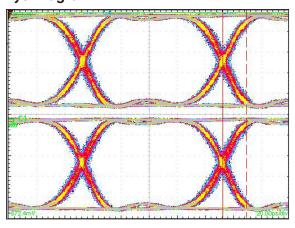






# 14 Gbps, FAST RISE TIME XOR / XNOR GATE

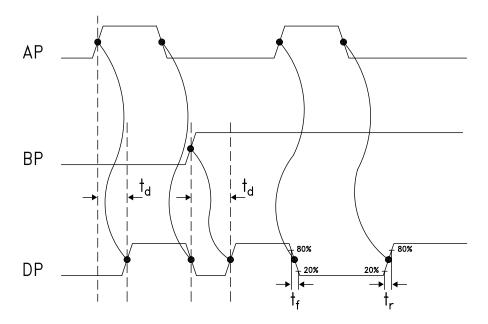
## Eye Diagram



#### [1] Test Conditions:

Pattern generated with an Agilent N4903A Serial BERT.
Eye Diagram presented on a Tektronix CSA 8000.
Device input = 10 Gbps PN code, Vin = 300 mVp-p differential.
Both output channels shown.

## **Timing Diagram**



#### **Truth Table**

Input		Outputs
A	В	D
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L
Notes: A = AP - AN B = BP - BN D = DP - DN	H - Positive voltage level L - Negative voltage level	





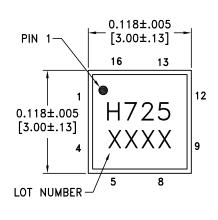
# 14 Gbps, FAST RISE TIME XOR / XNOR GATE

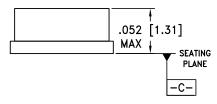
## **Absolute Maximum Ratings**

Power Supply Voltage (Vee)	-3.75 V to +0.5 V	
Input Signals	-2 V to +0.5 V	
Output Signals	-1.5 V to +1 V	
Continuous Pdiss (T = 85 °C) (derate 17 mW/°C above 85 °C)	0.68 W	
Thermal Resistance (R <sub>th j-p</sub> ) Worst case junction to package paddle	59 °C/W	
Maximum Junction Temperature	125 °C	
Storage Temperature	-65 °C to +150 °C	
Operating Temperature	-40 °C to +85 °C	
ESD Sensitivity (HBM)	Class 1C	



## **Outline Drawing**





#### **BOTTOM VIEW PIN 16** .013 [0.32] REF PIN 1 $\Box$ $\Box$ D **EXPOSED** -.083 [2.10] **GROUND** .059 [1.50] **PADDLE** SQUARE

#### NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05 mm DATUM -C-
- 6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
- 7. PADDLE MUST BE SOLDERED TO GND.

## Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC725LC3C	Alumina, White	Gold over Nickel	MSL3 <sup>[1]</sup>	H725 XXXX

<sup>[1]</sup> Max peak reflow temperature of 260 °C

<sup>[2] 4-</sup>Digit lot number XXXX





# 14 Gbps, FAST RISE TIME XOR / XNOR GATE

#### **Pin Descriptions**

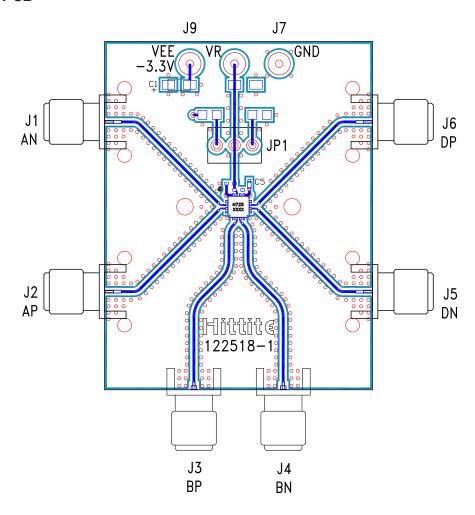
Pin Number	Function	Description	Interface Schematic	
1, 4, 5, 8, 9, 12	GND	These pins must be connected to a high-quality RF/DC ground.	⊖ GND =	
2, 3 6, 7	AN, AP BP, BN	Differential Data Inputs, Current Mode Logic (CML) referenced to positive supply.	GND GND SNN	
10, 11	DN, DP	Differential Data Outputs, Current Mode Logic (CML) referenced to positive supply	GND O GND  DP O DN	
13, 16	Vee	Negative Supply		
14, Package Base	GND	Supply Ground	GND =	
15	N/C	No Connection required. This pin may be connected to RF/DC ground without affecting performance.		





# 14 Gbps, FAST RISE TIME XOR / XNOR GATE

#### **Evaluation PCB**



#### List of Materials for Evaluation PCB 122520 [1]

Item	Description
J1 - J6	PCB Mount SMA RF Connectors
J7, J9	DC Pin
C1	4.7 μF Capacitor, Tantalum
C5	100 pF Capacitor, 0402 Pkg.
U1	HMC725LC3C High Speed Logic, XOR / XNOR
PCB [2]	122518 Evaluation Board

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed package base should be connected to GND. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

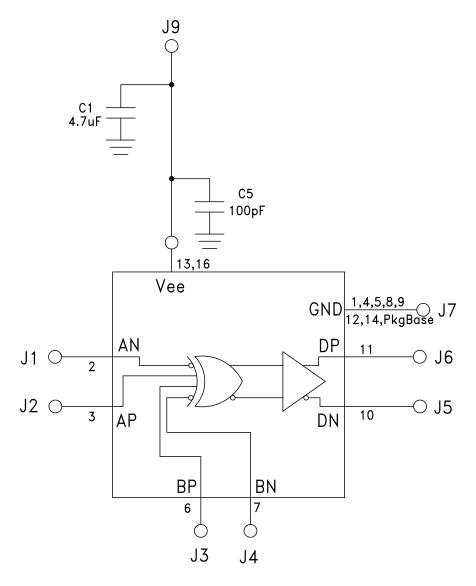
<sup>[2]</sup> Circuit Board Material: Arlon 25FR or Rogers 4350





# 14 Gbps, FAST RISE TIME XOR / XNOR GATE

## **Application Circuit**



# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Logic Gates category:

Click to view products by Analog Devices manufacturer:

Other Similar products are found below:

74HC85N NLU1G32AMUTCG NLVHC1G08DFT1G CD4068BE NL17SG32P5T5G NL17SG86DFT2G NLV14001UBDR2G
NLX1G11AMUTCG NLX1G97MUTCG 74LS38 74LVC32ADTR2G MC74HCT20ADTR2G NLV17SZ00DFT2G NLV17SZ02DFT2G
NLV74HC02ADR2G 74HC32S14-13 74LS133 M38510/30402BDA 74LVC1G86Z-7 74LVC2G08RA3-7 NLV74HC08ADTR2G
NLV74HC14ADR2G NLV74HC20ADR2G NLX2G86MUTCG 5962-8973601DA 74LVC2G02HD4-7 NLU1G00AMUTCG
74LVC2G32RA3-7 74LVC2G00HD4-7 NL17SG02P5T5G 74LVC2G00HK3-7 74LVC2G86HK3-7 NLX1G99DMUTWG
NLVVHC1G00DFT2G NLVHC1G08DFT2G NLV7SZ57DFT2G NLV74VHC04DTR2G NLV27WZ86USG NLV27WZ00USG
NLU1G86CMUTCG NLU1G08CMUTCG NL17SZ32P5T5G NL17SZ00P5T5G NL17SH02P5T5G 74AUP2G00RA3-7
NLV74HC02ADTR2G NLX1G332CMUTCG NL17SG86P5T5G NL17SZ05P5T5G NLV74VHC00DTR2G